



FOR IMMEDIATE RELEASE
March 26, 2021
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BUREAU OF INDUSTRY AND SECURITY
Office of Congressional and Public Affairs
(202) 482-1069

VIRTUAL FORUM FOR RISKS IN THE SEMICONDUCTOR MANUFACTURING AND ADVANCED PACKAGING SUPPLY CHAIN

WASHINGTON – On February 24, 2021, President Biden issued Executive Order 14017, “America’s Supply Chains,” focusing on the need for resilient, diverse, and secure supply chains to ensure U.S. economic prosperity and national security. The Executive Order directs the Secretary of Commerce to, within 100 days, submit a report to the President identifying risks in the semiconductor manufacturing and advanced packaging supply chains and proposing policy recommendations to address these risks.

On March 15, 2021, the Bureau of Industry and Security (BIS) published a notice of inquiry for public comments, *Risks in the Semiconductor Manufacturing and Advanced Packaging Supply Chain* (86 FR 14308). This March 15 notice requests written comments and information from the public to assist the Department of Commerce (the Department) in preparing the report required by the Executive Order with written comments due by April 5, 2021.

Additionally, on April 8, 2021, the Department will hold a virtual forum to allow participants to address the policy objectives listed in Executive Order 14017 as they affect the U.S. semiconductor manufacturing and advanced packaging supply chains. Public comments solicited through the forum will assist the Department in preparing the report required by Executive Order 14017. Representatives from the Department and other U.S. government agencies will make up the virtual forum panel.

The virtual forum will start at 2:00 p.m. Eastern Daylight Time (EDT) and will conclude at 5:00 p.m. EDT. Registration for the virtual forum closes at 5:00 p.m. EDT on April 1, 2021. Requests to make a presentation must be received by this time.

For more information on the virtual forum, to register for the event, and to request to present during the event, please visit <https://www.bis.doc.gov/semiconductorforum>.